IPC ASSOCIATION CONNEC	Material Compos © Copyright 2005. IPC international and Pan-A	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No. Homogeneous Mater					erials and N	als and Mfg Information				
upplier Info	rmation															
Company name*		Company unique ID			τ	Unique ID Authority					Respon	Response Date*				
nsemi											2023-0	2023-06-08				
Contact Name		Title - Contact			F	Phone - Contact*					Email	Email - Contact*				
Product-Env-Ste	ewards		Product Enviro Compliance]	NA					Produ	Product-Env-Stewards@onsemi.com			
uthorized Repr	esentative*	Title - Representative			F	Phone - Representative*				Email	Email - Representative*					
Product-Env-Ste	ewards	Product Enviro Compliance]	NA				Produ	Product-Env-Stewards@onsemi.com					
Reque	Requester Item Number M		Mfr Item Number Mfr Item Name			F		te Ve	Version		Manufacturing Site		Weight*	U	OM	Unit Type
		NCP8110	CP81109CMNTXG Single-Phase Voltage Interface		age Regulator with	SVID	2023-06-08		PH1			118.03	m	g	Each	
Ianufacturin	ng Proccess Information	on														
Terminal Plating / Grid Array Material			Germinal Base Alloy J-STD-020 MSL		-STD-020 MSL Rat	ing	Peak Process Body Temperature Max		x Time at Pe	ak Tempera	ature Nu	ımber of R	eflow Cycle	S		
Matte Tin (Sn) - annealed			CU Alloy 3		3		260 C		30 seco		nds 3					
omments																
TENTION: M	ISL 3 Rated item requires l	Bake and D	ry Pack (after	electrical test)												
or more inform	ation regarding material co	omposition	please refer to	page 3												

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybrominal contains a RoHS restricted substance inexcess encompass all such components. Supplier certi as of the date that Supplier completes this for Company acknowledges that Supplier may ha independently verified information provided by certification in this paragraph. If the Company	ted biphenyls and/or polybrominated dipheny of an applicable quantity limit, please indicate fies that it gathered the information it provident. Supplier acknowledges that Company will we relied on information provided by others in the supplier agrees that, at a minimum and the Supplier enter into a written agreements ource of the Supplier's liability and the Com-	2011/65/EU and implemented by the laws of the End ethers (each a "RoHS restricted substance") in except the below which, if any, RoHS exemption you believe in this form using appropriate methods to ensure rely on this certification in determining the compliant completing this form, and that Supplier may not have its suppliers have provided certifications regarding ent with respect to the identified part, the terms and capany's remedies for issues that arise regarding information in the provided certification in	sess of the applicable quantity limit identified able may apply. If the part is an assembly with low its accuracy and that such information is true annee of its products with European Union member ave independently verified such information. However, their contributions to the part, and those certifications of that agreement, including any warr	bove. If a homogeneous material within the part ver level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. It is involved in situations where Supplier has not ations are at least as comprehensive as the ranty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.48	mg	Supplier	Silicon (Si)	7440-21-3		3.48	mg
Die Attach Solder	3.37	mg	Supplier	Silver (Ag)	7440-22-4		0.0842	mg
			A	Lead (Pb)	7439-92-1	7a	3.1172	mg
			Supplier	Tin (Sn)	7440-31-5		0.1685	mg
Lead Frame	57.28	mg	Supplier	Silver (Ag)	7440-22-4		0.2291	mg
			Supplier	Tin (Sn)	7440-31-5		0.1432	mg
			Supplier	Zinc (Zn)	7440-66-6		0.126	mg
			Supplier	Chromium (Cr)	7440-47-3		0.1432	mg
			Supplier	Copper (Cu)	7440-50-8		56.6385	mg
Mold Compound-Black	49.82	mg		Epoxy resin	proprietary data		2.3415	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		4.982	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0498	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.1051	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.3415	mg
Plating	2.76	mg	Supplier	Tin (Sn)	7440-31-5		2.76	mg
Wire Bond - Au	1.32	mg	Supplier	Gold (Au)	7440-57-5		1.32	mg